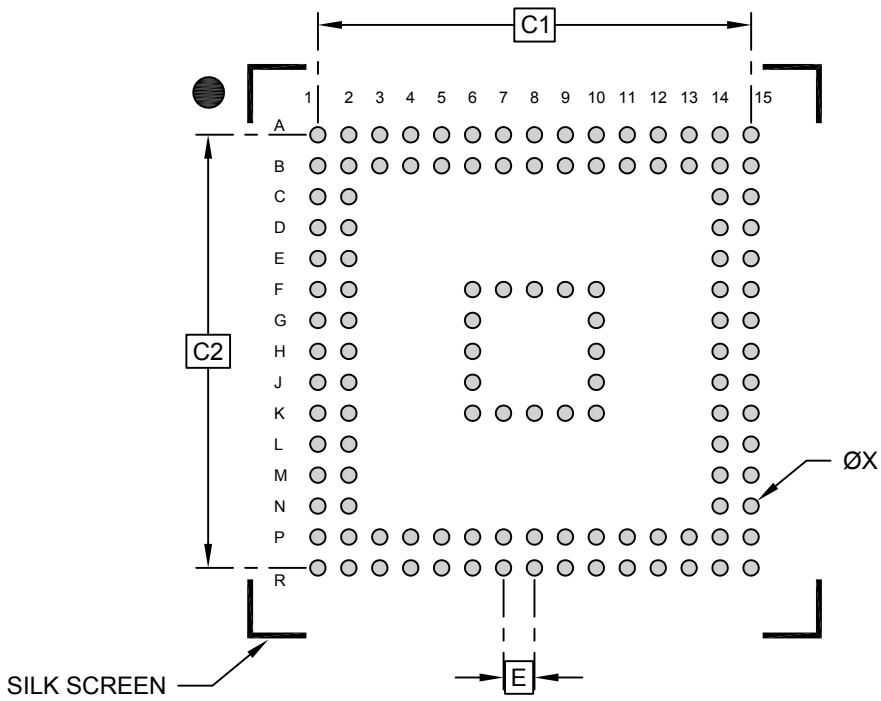


120-Ball Thin Fine Pitch Ball Grid Array Package (HEB) - 8x8 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1	7.00 BSC		
Contact Pad Spacing	C2	7.00 BSC		
Contact Pad Width (X20)	X		0.25	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.